

# 74VHC32 Quad 2-Input OR Gate

# **General Description**

The VHC32 is an advanced high speed CMOS 2-Input OR Gate fabricated with silicon gate CMOS technology. It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

The internal circuit is composed of 4 stages including buffer output, which provide high noise immunity and stable output. An input protection circuit ensures that 0V to 7V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5V to 3V systems and two supply systems such as battery back up. This circuit prevents device destruction due to mismatched supply and input voltages.

## **Features**

- Low Power Dissipation:  $I_{CC} = 2 \mu A \text{ (Max) at } T_A = 25^{\circ}\text{C}$
- High Noise Immunity: V<sub>NIH</sub> = V<sub>NIL</sub> = 28% V<sub>CC</sub> (Min)
- All inputs are equipped with a Power Down Protection Function
- Balanced Propagation Delays: t<sub>PLH</sub> ≃ t<sub>PHL</sub>
- Low Noise: V<sub>OLP</sub> = 0.8V (Max)
- Pin and Function Compatible with 74HC32

Commercial	Package Number	Package Description					
74VHC32M	M14A	14-Lead Molded JEDEC SOIC					
74VHC32SJ	M14D	14-Lead Molded EIAJ SOIC					
74VHC32MSC	MSC14	14-Lead Molded EIAJ Type 1 SSOP					
74VHC32MTC	MTC14	14-Lead Molded JEDEC Type 1 TSSOP					
74VHC32N	N14A	14-Lead Molded DIP					

Note: Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

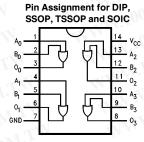
EIAJ Type I SSOP available Tape and Reel only, order MSCX.

### **Logic Symbol**

# 

TL/F/11518-1

### **Connection Diagram**



TL/F/11518-2

### **Truth Table**

puts
utputs

100 A	В	0 11			
M.Co	Н	Н			
1.100 [ 00	H.	Н			
H	L	Н			
M.Inf.	OM. L	L			

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### **Absolute Maximum Ratings** (Note 1)

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Supply Voltage (V<sub>CC</sub>) -0.5V to +7.0VDC Input Voltage (VIN) -0.5V to +7.0VDC Output Voltage (VOUT) -0.5V to  $V_{CC} + 0.5V$ Input Diode Current (I<sub>IK</sub>) -20 mAOutput Diode Current (IOK)  $\pm 20 \, \text{mA}$ DC Output Current (I<sub>OUT</sub>)  $\pm$  25 mA DC V<sub>CC</sub>/GND Current (I<sub>CC</sub>)  $\pm\,50~mA$ -65°C to +150°C Storage Temperature (T<sub>STG</sub>)

Lead Temperature (T<sub>L</sub>)
(Soldering, 10 seconds) 260°C

Note 1: Absolute Maximum Ratings are values beyond which the device may be damaged or have its useful life impaired. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. National does not recommend operation outside databook specifications.

# Recommended Operating Conditions

 $V_{CC} = 3.3V \pm 0.3V$  0 ~ 100 ns/V  $V_{CC} = 5.0V \pm 0.5V$  0 ~ 20 ns/V

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## **DC Characteristics for 'VHC Family Devices**

N	x 100	74VHC		74VHC T <sub>A</sub> = -40°C to +85°C		00 1.	Conditions			
Symbol Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C				Units				
		- XX 1	Min	Тур	Max	Min	Max	V.10V	COMIT	
V <sub>IH</sub> High Level Input Voltage		2.0 3.0-5.5	1.50 0.7 V <sub>CC</sub>		I.TW	1.50 0.7 V <sub>CC</sub>	WW.	VI	ON. CO	M.TW
V <sub>IL</sub>	Low Level Input Voltage	2.0 3.0-5.5	100 x		0.50 0.3 V <sub>CC</sub>	N	0.50 0.3 V <sub>CC</sub>	V	00 Y.C.	OM.I
V <sub>OH</sub>	High Level Output Voltage	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5	$O_{M}$	1.9 2.9 4.4	1	٧	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OH} = -50 \mu\text{A}$
		3.0 4.5	2.58 3.94	007 0 1	.coM	2.48 3.80		٧	W.100	$I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$
V <sub>OL</sub>	Low Level Output Voltage	2.0 3.0 4.5	WW.	0.0 0.0 0.0	0.1 0.1 0.1	M.TW	0.1 0.1 0.1	٧	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL} = 50 \mu A$
		3.0 4.5	MM		0.36 0.36	$O_{M,T}$	0.44 0.44	V	NWW.1	$I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$
I <sub>IN</sub>	Input Leakage Current	0-5.5	WW	11.1	±0.1	ONI.	±1.0	μΑ	$V_{IN} = 5.5V$	or GND
I <sub>CC</sub>	Quiescent Supply Current	5.5	W	NN	2.0	CON	20.0	μΑ	$V_{IN} = V_{CC}$	or GND

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# **DC Characteristics for 'VHC Family Devices**

100X.	MITH	10	74\	/HC	Units	Conditions
Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> =	25°C		
	CONT		Тур	Limit		
**V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	5.0	0.3	0.8	٧	$C_L = 50 \text{ pF}$
**V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>	5.0	-0.3	-0.8	v	$C_L = 50 \text{ pF}$
**V <sub>IHD</sub>	Minimum High Level Dynamic Input Voltage	5.0	V. 1003	3.5	V	$C_L = 50 \text{ pF}$
**V <sub>ILD</sub>	Maximum Low Level Dynamic Input Voltage	5.0	WW.100	1.5	V	C <sub>L</sub> = 50 pF

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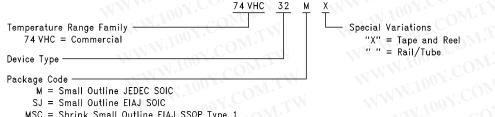
### **AC Electrical Characteristics**

Symbol Parameter	1007.0	V <sub>CC</sub> (V)	74VHC T <sub>A</sub> = 25°C			$74VHC$ $T_{A} = -40^{\circ}C$ $to +85^{\circ}C$		Units	Test Condition	
	Parameter									
	MM, 100X		Min	Тур	Max	Min	Max	M.J.		
t <sub>PHL</sub> , Propagation Delay t <sub>PLH</sub>	3.3	WT	5.5	7.9	1.0	9.5	ns	$C_{L} = 15  pF$		
	±0.3	Mr.	8.0	11.4	1.0	13.0	113	$\sqrt{C_L} = 50  pF$		
	W 1 10	W. 100	5.0	$M_{T}$	3.8	5.5	1.0	6.5	OM	$C_{L} = 15  pF$
WW.	±0.5	an.T	5.3	7.5	1.0	8.5	ns	$C_L = 50 pF$		
C <sub>IN</sub>	Input Capacitance	. NOV.	OF	4	10	MAN A.	10	pF	V <sub>CC</sub> = Ope	
C <sub>PD</sub>	Power Dissipation Capacitance	TOON	$CO_{M}$	14		WW	N.100	pF	(Note 1)	

Note 1: CPD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC}$  (opr.) =  $C_{PD}$  \*  $V_{CC}$  \*  $f_{IN}$  +  $I_{CC}$ /4 (per gate).

### Ordering Information

The device number is used to form part of a simplified purchasing code, where the package type and temperature range are defined as follows:



SJ = Small Outline EIAJ SOIC

MSC = Shrink Small Outline EIAJ SSOP Type 1

MTC = Thin Shrink Small Outline JEDEC TSSOP Type 1

N = Molded Plastic DIP

TL/F/11518-3

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<sup>\*\*</sup>Parameter guaranteed by design.

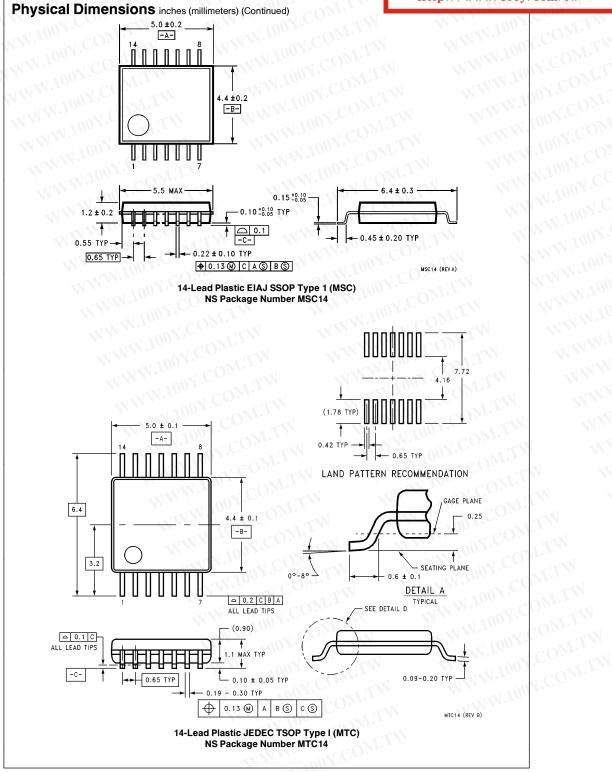
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Physical Dimensions inches (millimeters)  $\frac{0.335 - 0.344}{(8.509 - 8.738)}$ 0.228 - 0.244LEAD NO. 1 Ĥ 0.010 (0.254) MAX  $\frac{0.150 - 0.157}{(3.810 - 3.988)}$ 0.053 - 0.069 $\frac{0.010 - 0.020}{(0.254 - 0.508)}$ (1.346 - 1.753)8° MAX TYP ALL LEADS  $\frac{0.004 - 0.010}{(0.102 - 0.254)}$ SEATING PLANE 0.014 0.008 - 0.010 0.050 (1.270) TYP  $\frac{0.014-0.020}{(0.356-0.508)}\,\mathrm{TYP}$ (0.356)0.016 - 0.050(0.203-0.254) TYP ALL LEADS 0.008 (0.203) TYP (0.406 - 1.270) TYP ALL LEADS 0.004 (0.102) ALL LEAD TIPS 14-Lead Small Outline Integrated Circuit-JEDEC (M) NS Package Number M14A 0.394 - 0.402 (10.01 - 10.21)|12 || || 0.295 - 0.319 (7.493 - 8.103) 0.205 - 0.213 (5.207 - 5.410) H<sub>7</sub> H H 2 3 5 0.016 - 0.031 (0.406 - 0.787)DETAIL F 0.071 (1.803) REF 0.067 - 0.0830.006 - 0.010 $\overline{(1.702 - 2.108)}$ (0.152 - 0.254)-SEATING PLANE 0.049 (1.245) REF 0.050 0.000 - 0.010 (1.270) (0.000 - 0.254)0.014 - 0.020SEE DETAIL F (0.356 - 0.508)14-Lead Plastic EIAJ SOIC (SJ) NS Package Number M14D

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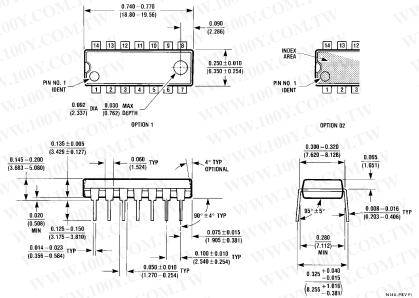
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### Physical Dimensions inches (millimeters) (Continued)



14-Lead Molded Dual-In-Line Package (MDIP) NS Package Number N14A

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